

ICS 31.200
CCS L 55



**NATIONAL STANDARD OF THE
PEOPLE'S REPUBLIC OF CHINA**

GB/T 35010.7-2018

**Semiconductor die products -- Part 7: XML schema for data
exchange**

Issued on: March 15, 2018

Implemented on: August 1, 2018

**Issued by: State Administration for Market Regulation, China National
Standardization Administration**

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Foreword

GB/T 35010 "Semiconductor Chip Products" is divided into the following parts.

- Part 1. Procurement and use requirements;
- Part 2. Data exchange format;
- Part 3. Guidelines for handling, packaging, and storage;
- Part 4. Chip user and supplier information table;
- Part 5. Electrical Simulation Requirements;
- Part 6. Thermal Simulation Requirements;
- Part 7. XML format for data exchange;
- Part 8. EXPRESS format for data exchange.

This part is Part 7 of GB/T 35010.

This section was drafted in accordance with the rules given in GB/T 1.1-2009.

This section uses the translation method equivalent to the use of IEC /T R62258-7.2007 "semiconductor chip product part 7. data exchange

XML format.

The Chinese documents that have a consistent correspondence with the normatively quoted international documents in this section are as follows.

- GB/T 2900 (all parts) Electrical terminology [IEC 60050 (all parts)]
- GB/T 35010.1-2018 Semiconductor chip products - Part 1. Procurement and use (IEC 62258-1.2009, IDT)
- GB/T 35010.2-2018 Semiconductor chip products Part 2. Data exchange format (IEC

62258-2.2011, IDT)

---GB/T 35010.4-2018 Semiconductor chip products Part 4. Chip user and supplier requirements (IEC /TR

62258-4.2012, IDT)

--- GB/T 35010.5-2018 Semiconductor chip products - Part 5. Electrical simulation requirements (IEC 62258-5.2006, IDT)

--- GB/T 35010.6-2018 Semiconductor chip products - Part 6. Thermal simulation requirements (IEC 62258-6.2006, IDT)

This section made the following editorial changes.

--- Deleted the third paragraph of Chapter 5 of IEC /T R62258-7.2007 on the electronic text of IEC /T R62258-7.2007

Take the method and use the required content;

--- Deleted references.

1 Scope

This part of GB/T 35010 is used to guide the production, supply and use of semiconductor chip products. One of the semiconductor chip products includes.

--- Wafers;

---Single bare chip;

--- Chips and wafers with interconnect structures;

--- Minimal or partially packaged chips and wafers.

This section specifies an XML format that defines the elements required for data exchange to meet IEC 62258-1, IEC 62258-

5. Implementation requirements of IEC 62258-6, supplementing the exchange structure defined in IEC 62258-2. This section is also complementary and compatible

Questionnaire in IEC /T R62258-4.

2 Normative references

The following documents are indispensable for the application of this document. For dated references, only dated versions apply to this article

Pieces. For undated references, the latest version (including all amendments) applies to this document.

IEC 60050 (all parts) Electrical vocabulary (International Electrotechnical Vocabulary)

IEC 62258-1 Semiconductor chip products Part 1. Procurement and use requirements
(Semiconductor die products-Part

1 Requirements for procurement and use)

IEC 62258-2 Semiconductor chip products Part 2. Data interchange formats
(Semiconductor die products-Part 2.

Exchangedataformats)

IEC /TR62258-4 Semiconductor chip products Part 4. Chip user and supplier requirements
(Semiconductor die

products-Part 4. Questionnaire for die users and suppliers)

IEC 62258-5 Semiconductor chip products - Part 5. Electrical simulation requirements
(Semiconductor die products-Part 5.

Requirements for information concerning electrical simulation)

IEC 62258-6 Semiconductor chip products Part 6. Thermal simulation requirements
(Semiconductor die products-Part 6. Re-

quirements for information concerning thermal simulation)

3 Terms and definitions

The terms and definitions defined by IEC 60050 (all parts) and IEC 62258-1 apply to this document.

4 General

The format in this section is consistent with Extensible Markup Language (XML).

This section requires chip device suppliers to provide users with the necessary and sufficient stages for the design, procurement, manufacturing, and testing of chip devices.

Information. The format in Appendix A defines an exchange mechanism that builds information for statements in the XML language. This is also for

To achieve the purpose of compliance with this section.